



$V_{RSM}$ V	$V_{RRM}, V_{DRM}$ V	$I_D = 53 \text{ A}$ (full conduction) ( $T_s = 100^\circ\text{C}$ ) SKD 53/04 SKD 53/08 SKD 53/12 SKD 53/14 SKD 53/16 SKD 53/18
500	400	
900	800	
1300	1200	
1600	1400	
1700	1600	
1900	1800	

## Power Bridge Rectifiers

### SKD 53

### Features

- Glass passivated silicon chips
- Low thermal impedance through use of direct copper bonded aluminum substrate (DCB) base plate
- Blocking voltage up to 1800 V
- Suitable for PCB mounting and wave soldering
- For applications with high vibrations we recommend to fasten the bridge to the pcb with 4 selftapping screw

### Typical Applications

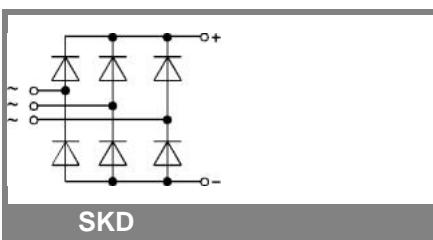
- Three phase rectifiers for power supplies
- Input rectifiers for variable frequency drives
- Rectifiers for DC motor field supplies
- Battery charger rectifiers

1) Freely suspended or mounted on an insulator

2) Mounted on a painted metal sheet of min. 250 x 250 x 1 mm

3)  $T_{solder} = 250 \pm 10^\circ\text{C}$  (10 s)

Symbol	Conditions	Values	Units
$I_D$	$T_s = 100^\circ\text{C}$	53	A
	$T_a = 45^\circ\text{C}$ ; isolated <sup>1)</sup>	4	A
	$T_a = 45^\circ\text{C}$ ; chassis <sup>2)</sup>	18	A
	$T_a = 45^\circ\text{C}$ ; P5A/100 (R4A/120)	27 (29)	A
	$T_a = 35^\circ\text{C}$ ; P1A/120F	63	A
$I_{FSM}$	$T_{vj} = 25^\circ\text{C}$ ; 10 ms	370	A
	$T_{vj} = 150^\circ\text{C}$ ; 10 ms	270	A
$i^2t$	$T_{vj} = 25^\circ\text{C}$ ; 8,3 ... 10 ms	685	A <sup>2</sup> s
	$T_{vj} = 150^\circ\text{C}$ ; 8,3 ... 10 ms	365	A <sup>2</sup> s
$V_F$ $V_{(TO)}$	$T_{vj} = 25^\circ\text{C}$ ; $I_F = 50 \text{ A}$	max. 1,5	V
	$T_{vj} = 150^\circ\text{C}$	max. 0,8	V
$r_T$	$T_{vj} = 150^\circ\text{C}$	max. 13	mΩ
$I_{RD}$	$T_{vj} = 25^\circ\text{C}$ ; $V_{DD} = V_{DRM}$ ; $V_{RD} = V_{RRM}$	max. 0,2	mA
	$T_{vj} = 150^\circ\text{C}$ ; $V_{RD} = V_{RRM}$	4	mA
$R_{th(j-s)}$	per diode	1,9	K/W
	total	0,317	K/W
$R_{th(j-a)}$	isolated <sup>1)</sup>	14,92	K/W
	chassis <sup>2)</sup>	2,92	K/W
$T_{vj}$		- 40 ... + 150	°C
$T_{stg}$		- 40 ... + 125 <sup>3)</sup>	°C
$V_{isol}$	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3600 ( 3000 )	V
$M_s$	to heatsink; SI units	2 ± 15 %	Nm
$M_t$		5 * 9,81	m/s <sup>2</sup>
$a$		30	g
$m$			
Case		G 55	



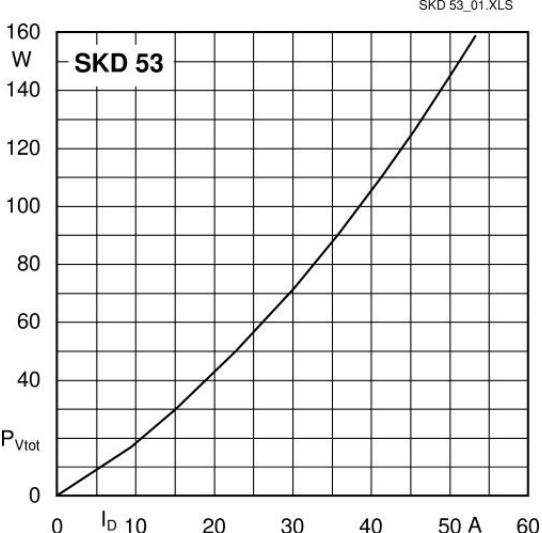


Fig. 3L Power dissipation vs. output current

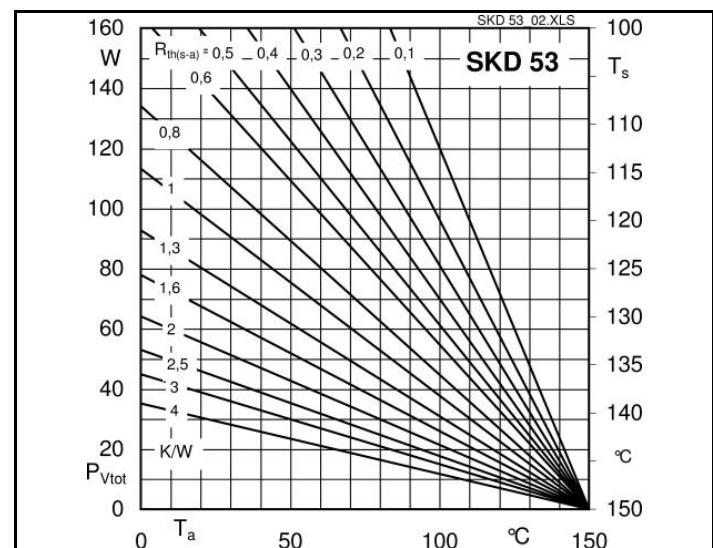
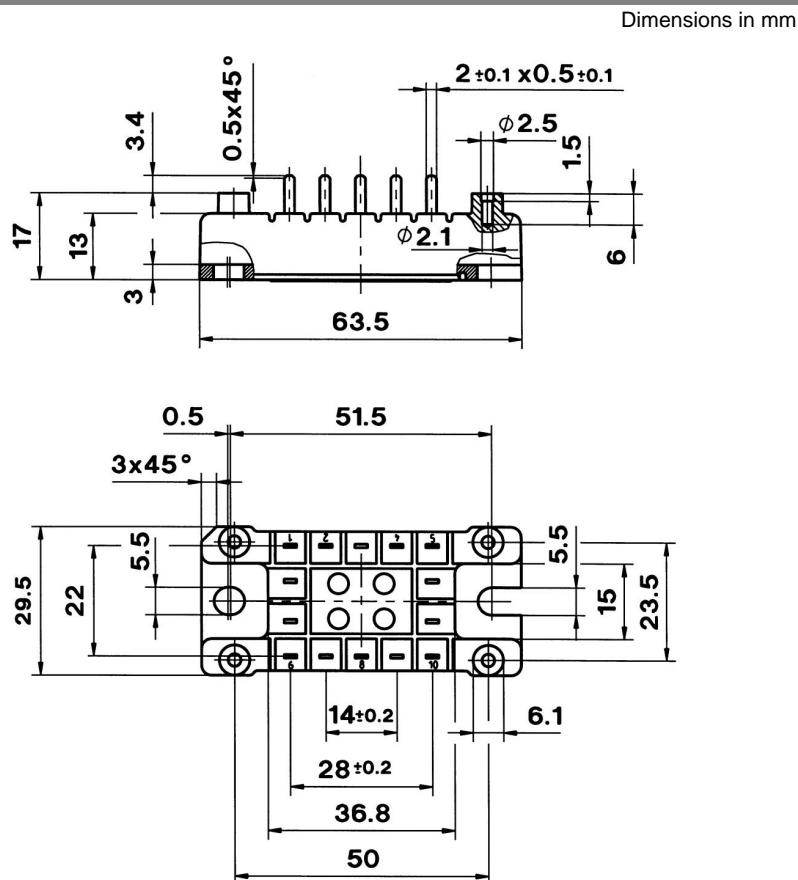


Fig. 3R Power dissipation vs. heatsink temperature



Case G 55

